



Parameter	Rating	Units
Blocking Voltage	250	V _P
Load Current	170	mA _{rms} / mA _{DC}
On-Resistance (max)	20	Ω

Features

- 3750V_{rms} Input/Output Isolation
- Low Drive Power Requirements (TTL/CMOS Compatible)
- FCC Compatible
- VDE Compatible
- No EMI/RFI Generation
- No Moving Parts
- High Reliability
- Arc-Free With No Snubbing Circuits
- Small 8-Pin Package
- Machine Insertable, Wave Solderable
- Surface Mount and Tape & Reel Versions Available

Applications

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hook Switch
 - Dial Pulsing
 - Ground Start
 - Ringing Injection
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The TS122 integrated circuit device combines a 250V, normally open (1-Form-A) relay with an optocoupler in a single package. The relay, with enhanced peak load current handling capability, uses optically coupled MOSFET technology to provide 3750V_{rms} of input to output isolation.

Its optically coupled relay outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient GaAlAs infrared LED.

Telecom circuit designers, using the TS122, can now take advantage of two discrete functions in a single component that uses less space than traditional discrete component solutions.

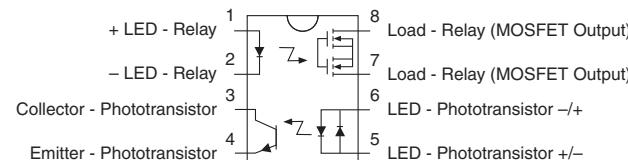
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950 Certified Component: TUV Certificate: B 10 05 49410 006

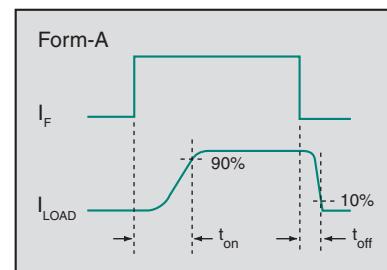
Ordering Information

Part #	Description
TS122	8-Pin DIP (50/Tube)
TS122P	8-Pin Flatpack (50/Tube)
TS122PTR	8-Pin Flatpack (1000/Reel)
TS122S	8-Pin Surface Mount (50/Tube)
TS122STR	8-Pin Surface Mount (1000/Reel)

Pin Configuration



Switching Characteristics of Normally Open Devices



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Relay Blocking Voltage	250	V _P
Input Power Dissipation ¹	150	mW
Input Control Current, Relay	50	mA
Peak (10ms)	1	A
Reverse Input Voltage	5	V
Input Control Current, Detector	100	mA
Total Power Dissipation ²	800	mW
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C

² Derate linearly 6.67 mW / °C

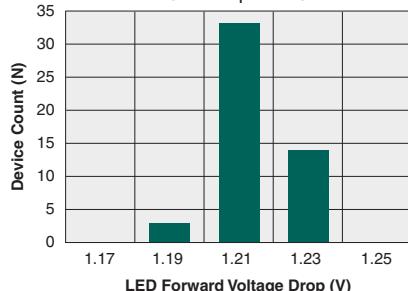
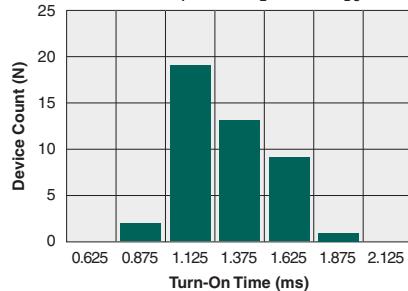
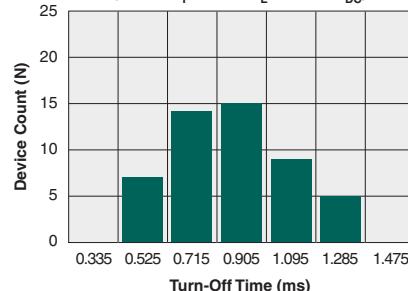
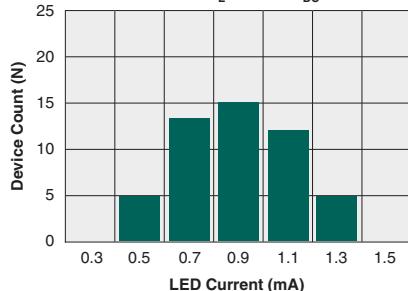
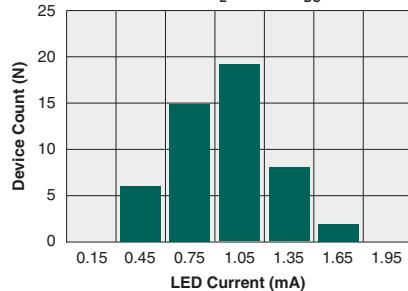
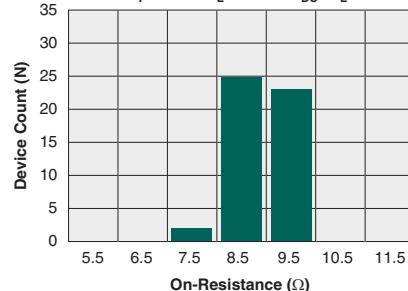
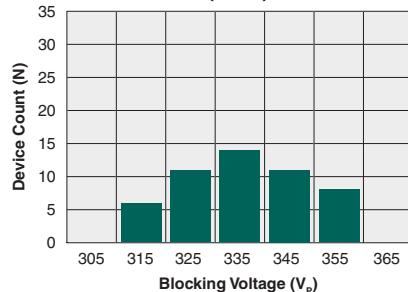
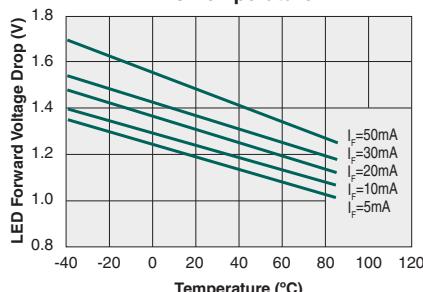
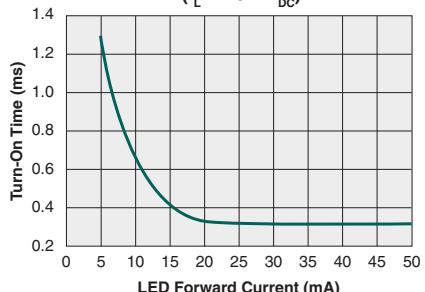
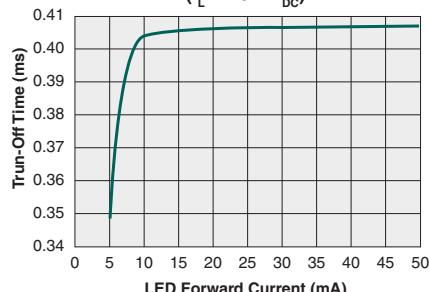
Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics @25°C: Relay Section

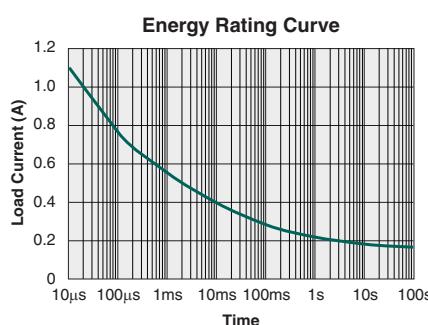
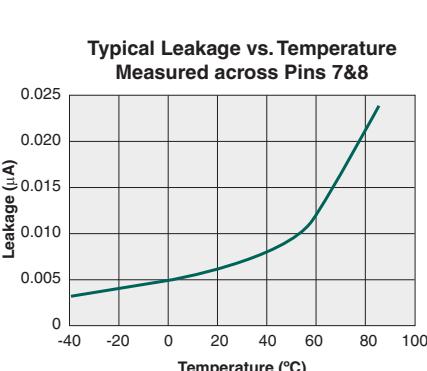
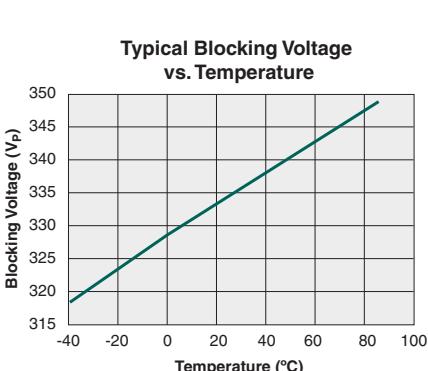
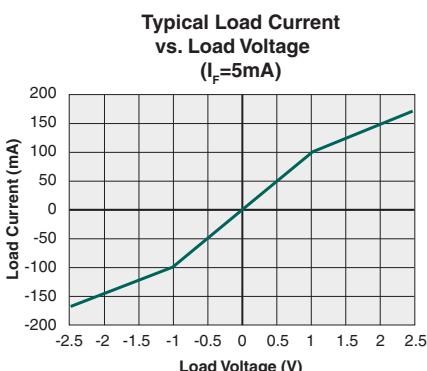
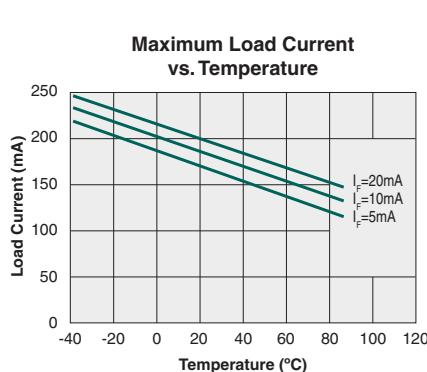
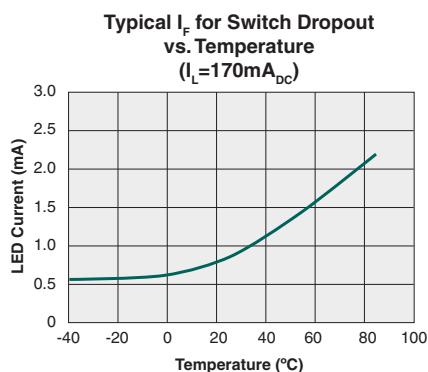
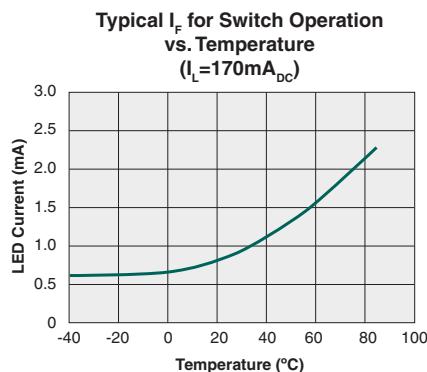
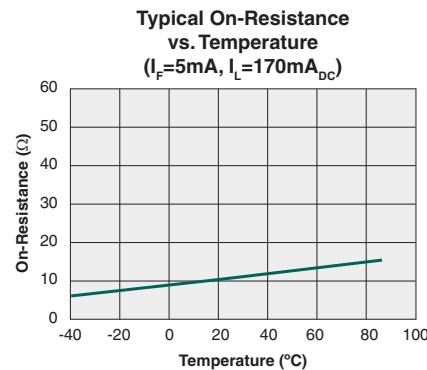
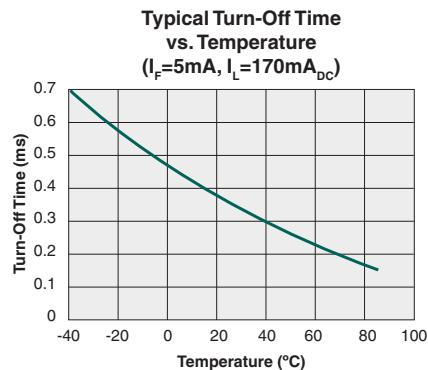
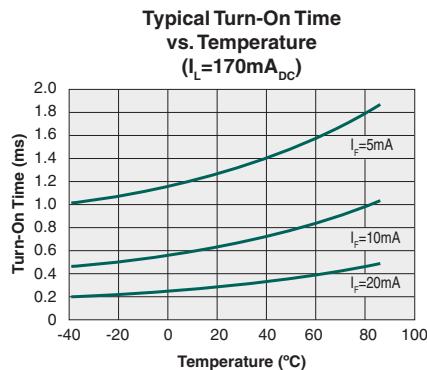
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current						
Continuous	-	I _L	-	-	170	mA _{rms} / mA _{DC}
Peak	t=10ms	I _{LPK}	-	-	±400	mA _P
On-Resistance	I _L =170mA	R _{ON}	-	12	20	Ω
Off-State Leakage Current	V _L =250V	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On		t _{on}	-	-	5	ms
Turn-Off	I _F =5mA, V _L =10V	t _{off}	-	-	5	ms
Output Capacitance	V _L =50V, f=1MHz	C _{OUT}	-	50	-	pF
Input Characteristics						
Input Control Current to Activate	I _L =170mA	I _F	-	-	5	mA
Input Dropout Current to Deactivate	-	I _F	0.4	0.7	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Common Characteristics						
Input to Output Capacitance	-	C _{I/O}	-	3	-	pF

Electrical Characteristics @25°C: Detector Section

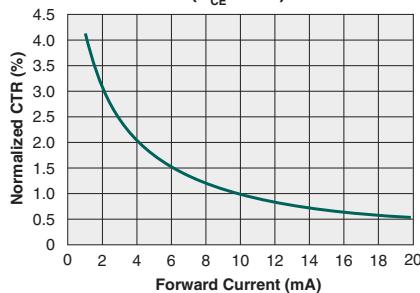
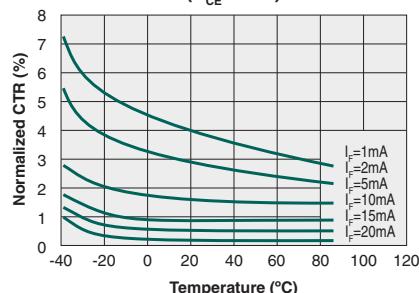
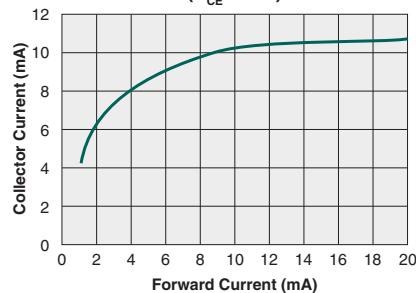
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Phototransistor Blocking Voltage	I _C =10μA	BV _{CEO}	20	50	-	V
Phototransistor Dark Current	V _{CE} =5V, I _F =0mA	I _{CEO}	-	50	500	nA
Saturation Voltage	I _C =2mA, I _F =16mA	V _{SAT}	-	0.3	0.5	V
Current Transfer Ratio	I _F =6mA, V _{CE} =0.5V	CTR	33	100	-	%
Input Characteristics						
Input Control Current	I _C =2mA, V _{CE} =0.5V	I _F	-	2	6	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Input Current (Detector must be off)	I _C =1μA, V _{CE} =5V	I _F	5	25	-	μA
Input to Output Capacitance	-	-	-	3	-	pF
Isolation, Input to Output	-	V _{I/O}	3750	-	-	V _{rms}

RELAY PERFORMANCE DATA @25°C (Unless Otherwise Noted)*
**Typical LED Forward Voltage Drop
(N=50, $I_F=5\text{mA}$)**

**Typical Turn-On Time
(N=50, $I_F=5\text{mA}$, $I_L=170\text{mA}_{\text{DC}}$)**

**Typical Turn-Off Time
(N=50, $I_F=5\text{mA}$, $I_L=170\text{mA}_{\text{DC}}$)**

**Typical I_F for Switch Operation
(N=50, $I_L=170\text{mA}_{\text{DC}}$)**

**Typical I_F for Switch Dropout
(N=50, $I_L=170\text{mA}_{\text{DC}}$)**

**Typical On-Resistance Distribution
(N=50, $I_F=5\text{mA}$, $I_L=170\text{mA}_{\text{DC}}$, $V_L=250\text{V}$)**

**Typical Blocking Voltage Distribution
(N=50)**

**Typical LED Forward Voltage Drop
vs. Temperature**

**Typical Turn-On Time
vs. LED Forward Current
($I_L=170\text{mA}_{\text{DC}}$)**

**Typical Turn-Off Time
vs. LED Forward Current
($I_L=170\text{mA}_{\text{DC}}$)**


* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

RELAY PERFORMANCE DATA @25°C (Unless Otherwise Noted)*


* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

DETECTOR PERFORMANCE DATA @25°C (Unless Otherwise Noted)*
**Typical Normalized CTR
vs. Forward Current
($V_{CE}=0.5V$)**

**Typical Normalized CTR
vs. Temperature
($V_{CE}=0.5V$)**

**Typical Collector Current
vs. Forward Current
($V_{CE}=0.5V$)**


* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity

 All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
TS122 / TS122P / TS122S	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

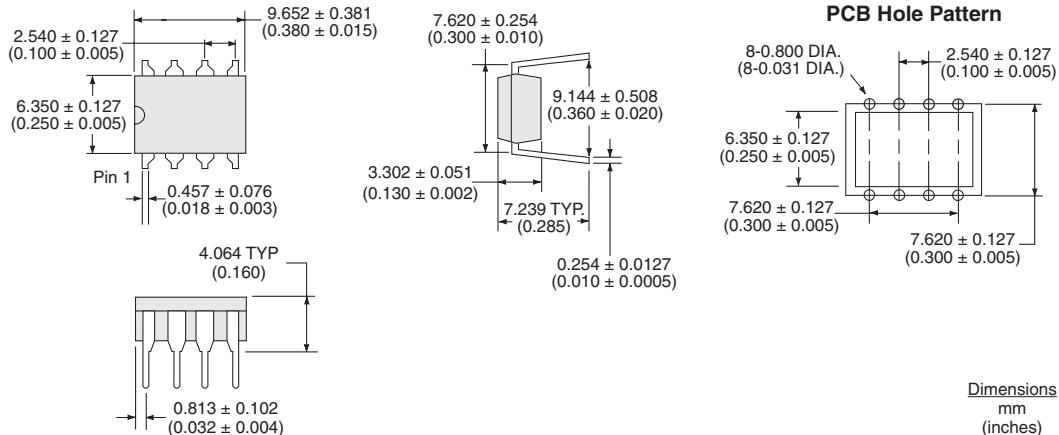
This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
TS122 / TS122S	250°C for 30 seconds
TS122P	260°C for 30 seconds

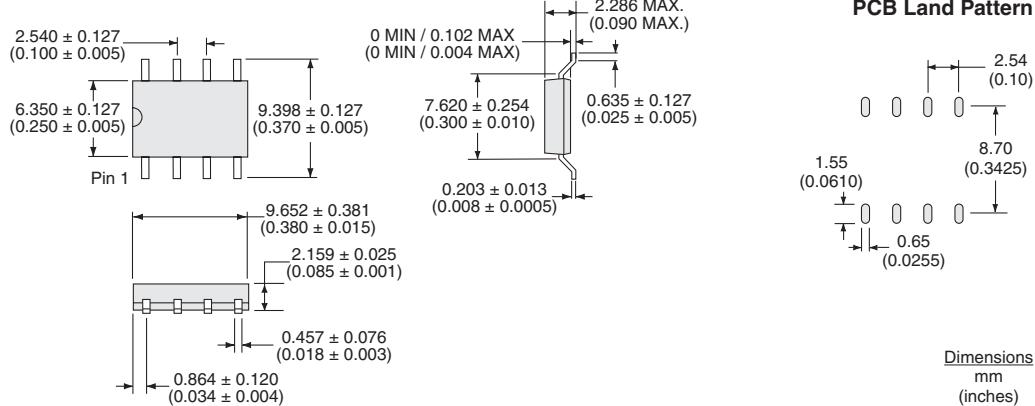
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

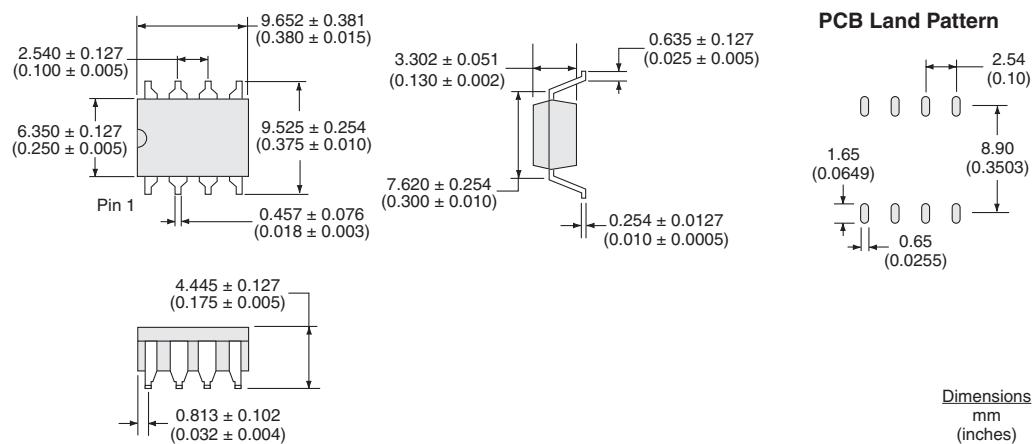


Mechanical Dimensions
TS122


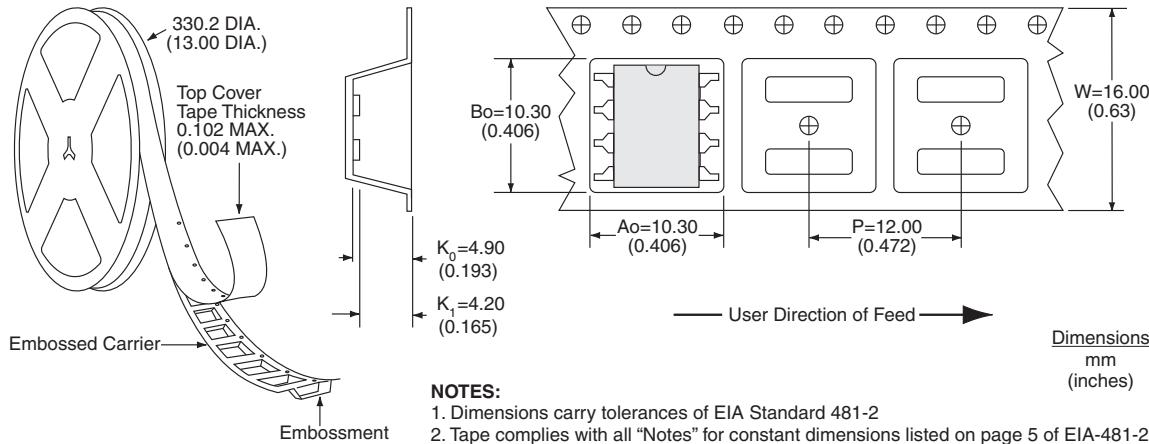
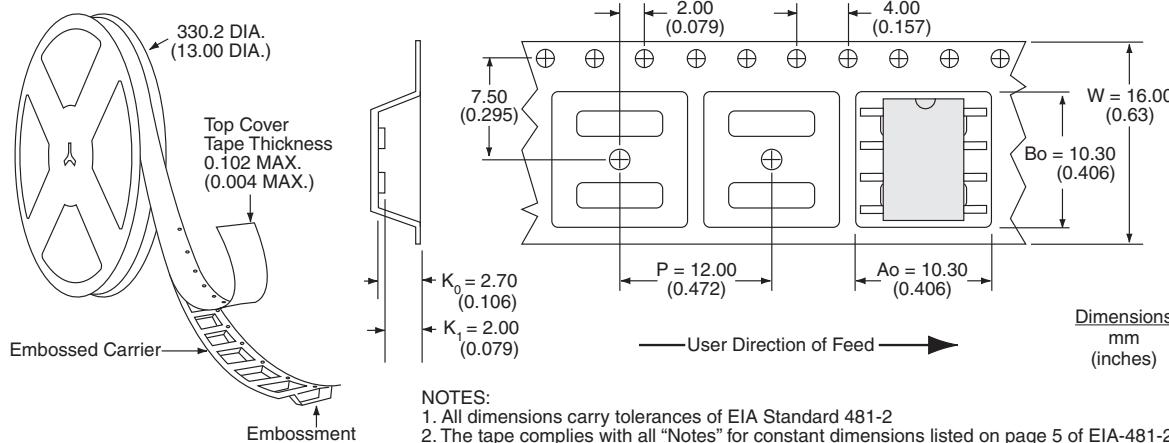
Dimensions
mm
(inches)

TS122P


Dimensions
mm
(inches)

TS122S


Dimensions
mm
(inches)

TS122STR Tape & Reel

TS122PTR Tape & Reel


For additional information please visit our website at: www.ixysic.com

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